

APPENDIX B
VERSION WITH MARKINGS TO SHOW CHANGES MADE
37 C.F.R. § 1.121(b)(iii) AND (c)(ii)

CLAIMS:

4. (Amended) A power MOSFET comprising, in combination[;], a P type substrate; an epitaxially deposited N type layer deposited atop said substrate and having a substantially constant concentration; a plurality of spaced trenches having vertical walls extending through said epitaxial layer; a thin gate oxide on said vertical walls and conductive P type polysilicon deposited into said trenches to define a polysilicon gate; a P type source region formed adjacent the walls of each of said trenches and diffused into the top of said epitaxial layer; a source contact connected to at least said source regions; a drain contact connected to said substrate; whereby said MOSFET has a reduced on resistance.